

LNPTM THERMOCOMPTM COMPOUND LCF62E

LCF-1008 EM REGION AMERICAS

DESCRIPTION

LNP THERMOCOMP LCF62E compound is based on Polyetheretherketone (PEEK) resin containing 10% carbon fiber and 30% glass fiber. Added features of this grade include: Easy Molding, Electrically Conductive.

GENERAL INFORMATION	
Features	Electrically Conductive, Good Processability, Carbon fiber filled, High stiffness/Strength, High temperature resistance
Fillers	Carbon Fiber, Glass Fiber
Polymer Types	Polyetheretherketone (PEEK)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Electrical and Electronics	Electronic Components, Mobile Phone - Computer - Tablets
Industrial	Electrical, Material Handling

TYPICAL PROPERTY VALUES

PROPERTIES TYPICAL VALUES UNITS **TEST METHODS** MECHANICAL⁽¹⁾ Tensile Stress, brk, Type I, 5 mm/min 203 MPa ASTM D638 Tensile Strain, brk, Type I, 5 mm/min 0.8 % ASTM D638 Tensile Modulus, 5 mm/min 62980 MPa ASTM D638 Flexural Stress, brk, 1.3 mm/min, 50 mm span 296 MPa ASTM D790 Flexural Modulus, 1.3 mm/min, 50 mm span 17340 MPa ASTM D790 Tensile Stress, break, 5 mm/min 196 MPa ISO 527 ISO 527 Tensile Strain, break, 5 mm/min 0.7 % Tensile Modulus, 1 mm/min 41090 MPa ISO 527 **Flexural Stress** 391 MPa ISO 178 Flexural Modulus, 2 mm/min 36490 MPa ISO 178 IMPACT (1) Izod Impact, unnotched, 23°C 711 J/m ASTM D4812 Izod Impact, notched, 23°C 80 ASTM D256 J/m Instrumented Dart Impact Total Energy, 23°C ASTM D3763 17 Izod Impact, unnotched 80*10*4 +23°C 47 kJ/m² ISO 180/1U Izod Impact, notched 80*10*4 +23°C 8 kJ/m² ISO 180/1A THERMAL (1) HDT, 0.45 MPa, 3.2 mm, unannealed °C 290 ASTM D648 HDT, 1.82 MPa, 3.2mm, unannealed 290 °C ASTM D648 HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm °C ISO 75/Bf 290

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CHEMISTRY THAT MATTERS

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PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	290	°C	ISO 75/Af
PHYSICAL ⁽¹⁾			
Specific Gravity	1.57	-	ASTM D792
Density	1.57	g/cm³	ASTM D792
Moisture Absorption, (23°C/50% RH/24 hrs)	0.02	%	ASTM D570
Mold Shrinkage, flow, 24 hrs ⁽²⁾	0.09 – 2	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	1 – 3	%	ASTM D955
Moisture Absorption (23°C / 50% RH)	0.02	%	ISO 62
INJECTION MOLDING (3)			
Drying Temperature	150	°C	
Drying Time	4 - 6	Hrs	
Front - Zone 3 Temperature	380 - 400	°C	
Middle - Zone 2 Temperature	380 - 400	°C	
Rear - Zone 1 Temperature	370 – 380	°C	
Mold Temperature	175 – 190	°C	
Back Pressure	0.3 – 0.7	MPa	
Screw Speed	60 – 100	rpm	

(1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.

(2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.

(3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

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